

US00D964969S

(12) **United States Design Patent**  
**Xun et al.**

(10) **Patent No.:** **US D964,969 S**

(45) **Date of Patent:** **\*\* Sep. 27, 2022**

(54) **EARPHONE**  
(71) Applicant: **BEIJING XIAOMI MOBILE SOFTWARE CO., LTD.**, Beijing (CN)  
(72) Inventors: **Keliang Xun**, Beijing (CN); **Weiwei Chen**, Beijing (CN); **Qing Li**, Beijing (CN); **Ruijiang Wang**, Beijing (CN); **Bin Liu**, Beijing (CN); **Yifan Huang**, Beijing (CN)  
(73) Assignee: **Beijing Xiaomi Mobile Software Co., Ltd.**, Beijing (CN)

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(Continued)

(\*\*) Term: **15 Years**

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(21) Appl. No.: **35/512,044**

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(22) Filed: **Jun. 4, 2021**

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(80) **Hague Agreement Data**

Int. Filing Date: **Jun. 4, 2021**  
Int. Reg. No.: **DM/214729**  
Int. Reg. Date: **Jun. 4, 2021**  
Int. Reg. Pub. Date: **Jun. 25, 2021**

*Primary Examiner* — L. A. Grabenstetter  
(74) *Attorney, Agent, or Firm* — Amster, Rothstein & Ebenstein LLP

(30) **Foreign Application Priority Data**

Dec. 7, 2020 (CN) ..... 202030750811.X

(51) **LOC (13) Cl.** ..... **14-01**

(52) **U.S. Cl.**  
USPC ..... **D14/223**

(58) **Field of Classification Search**  
USPC ..... D14/192, 205, 206, 223, 372; D24/106, D24/174; D13/107–110, 118  
CPC ..... G10K 11/1781; G10K 2210/1081; H04R 2420/07; H04R 1/083; H04M 1/6066  
See application file for complete search history.

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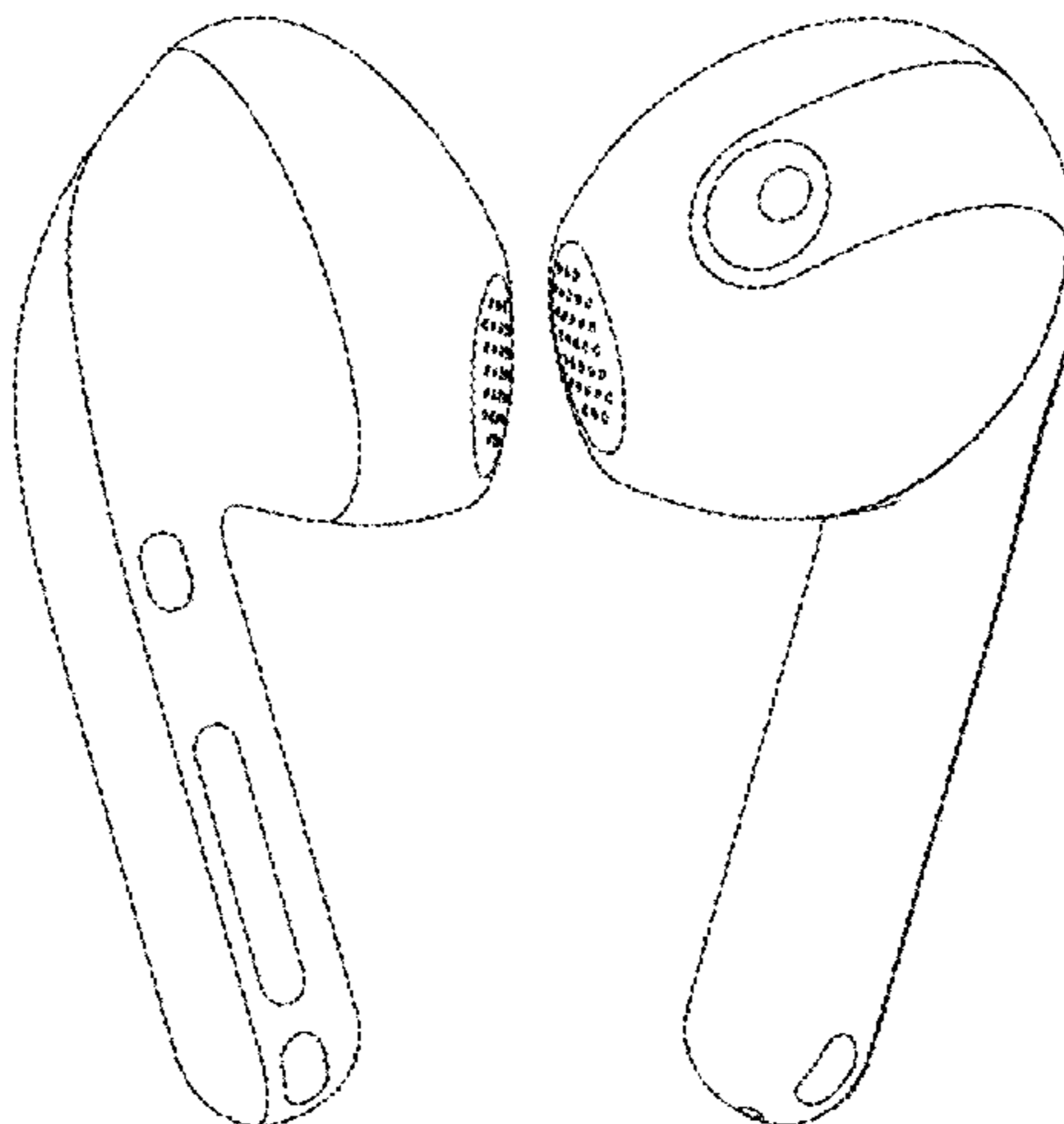
(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

**DESCRIPTION**

1. Earphone  
1.1 is a front elevation view of an earphone showing our new design;  
1.2 is a back elevation view thereof;  
1.3 is a left side elevation view thereof;  
1.4 is a right side elevation view thereof;  
1.5 is a top plan view thereof;  
1.6 is a bottom plan view thereof;  
1.7 is a front, right side perspective view thereof; and  
1.8 is a back, left side perspective view thereof.

**1 Claim, 8 Drawing Sheets**



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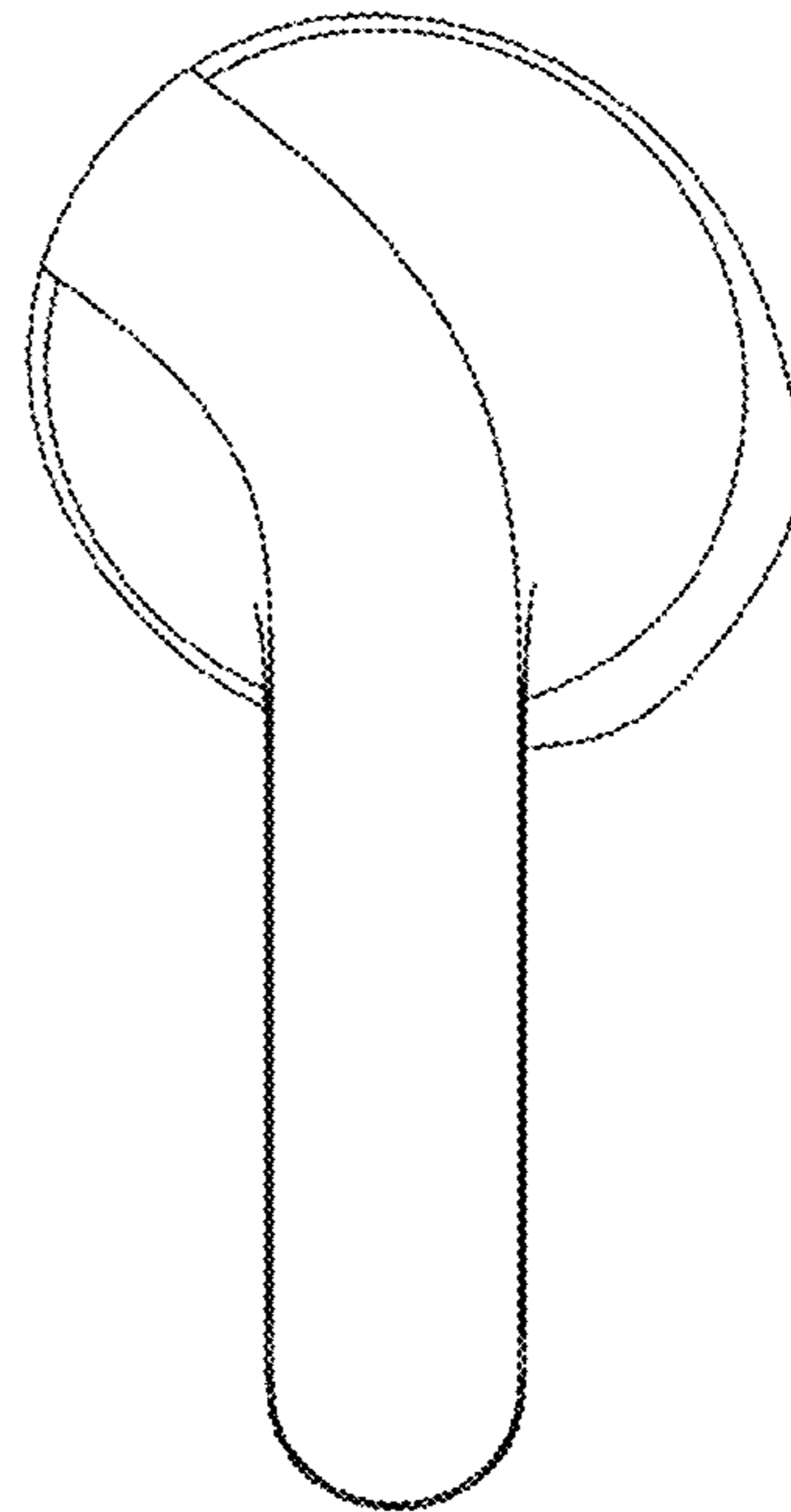
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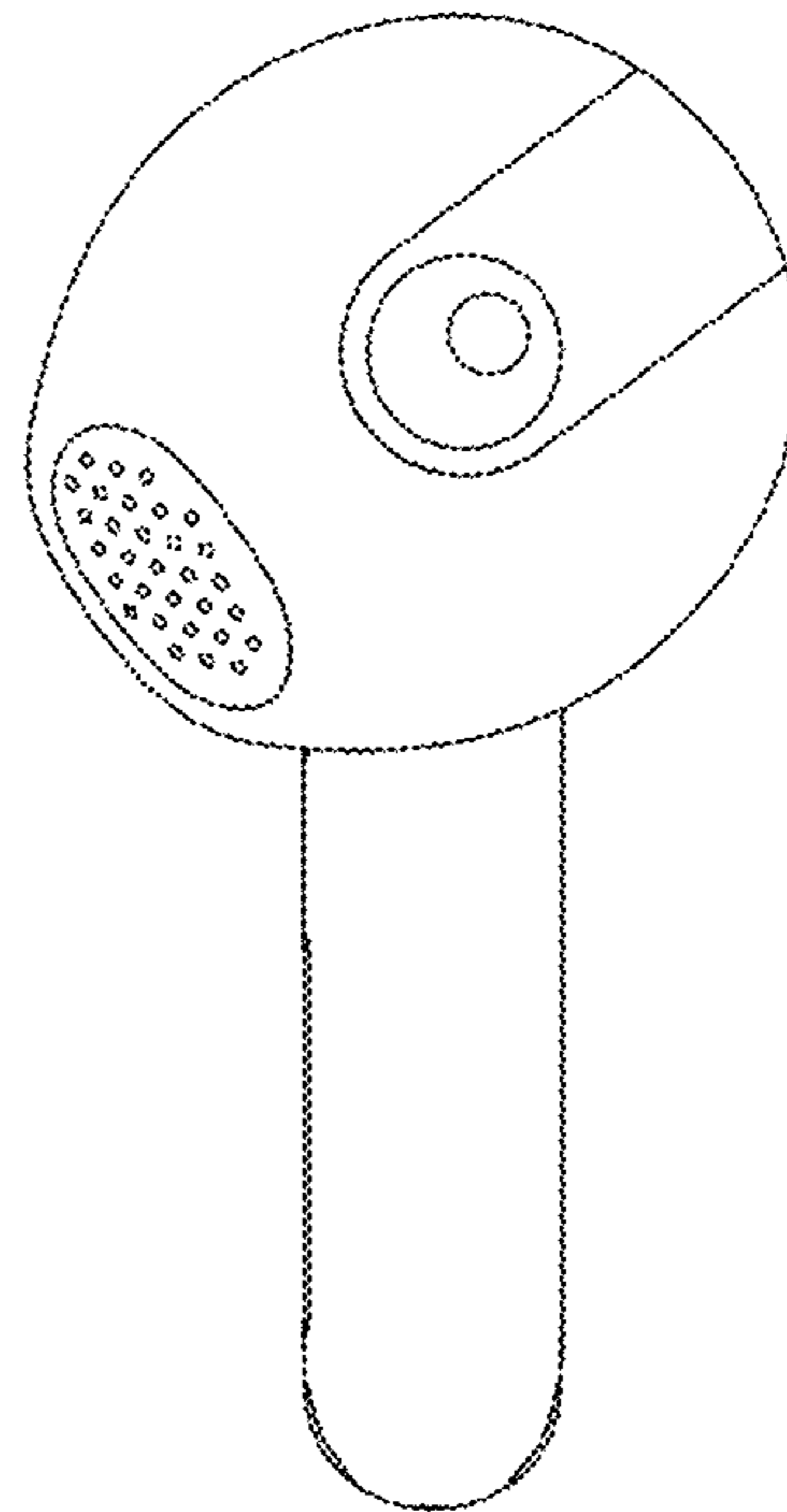
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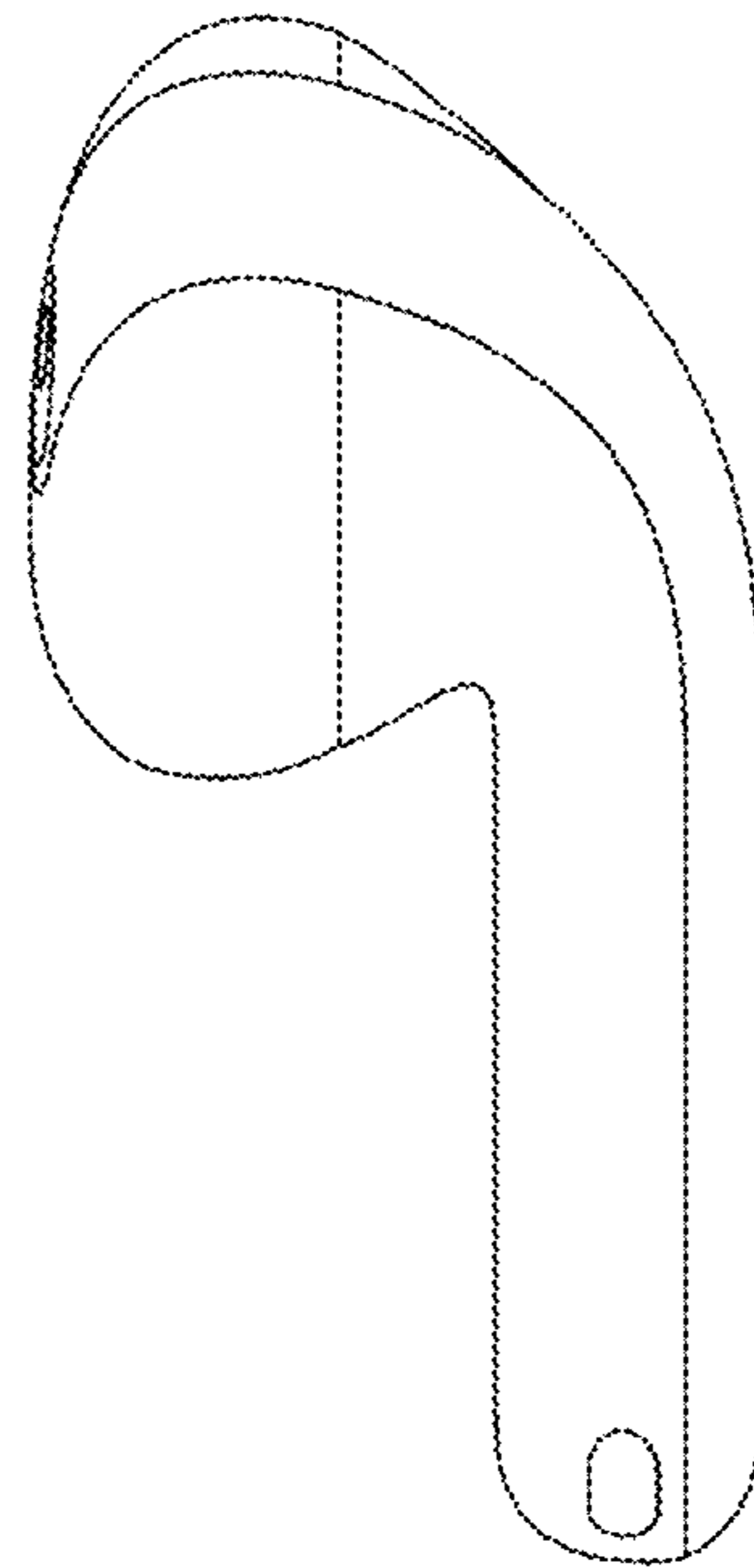
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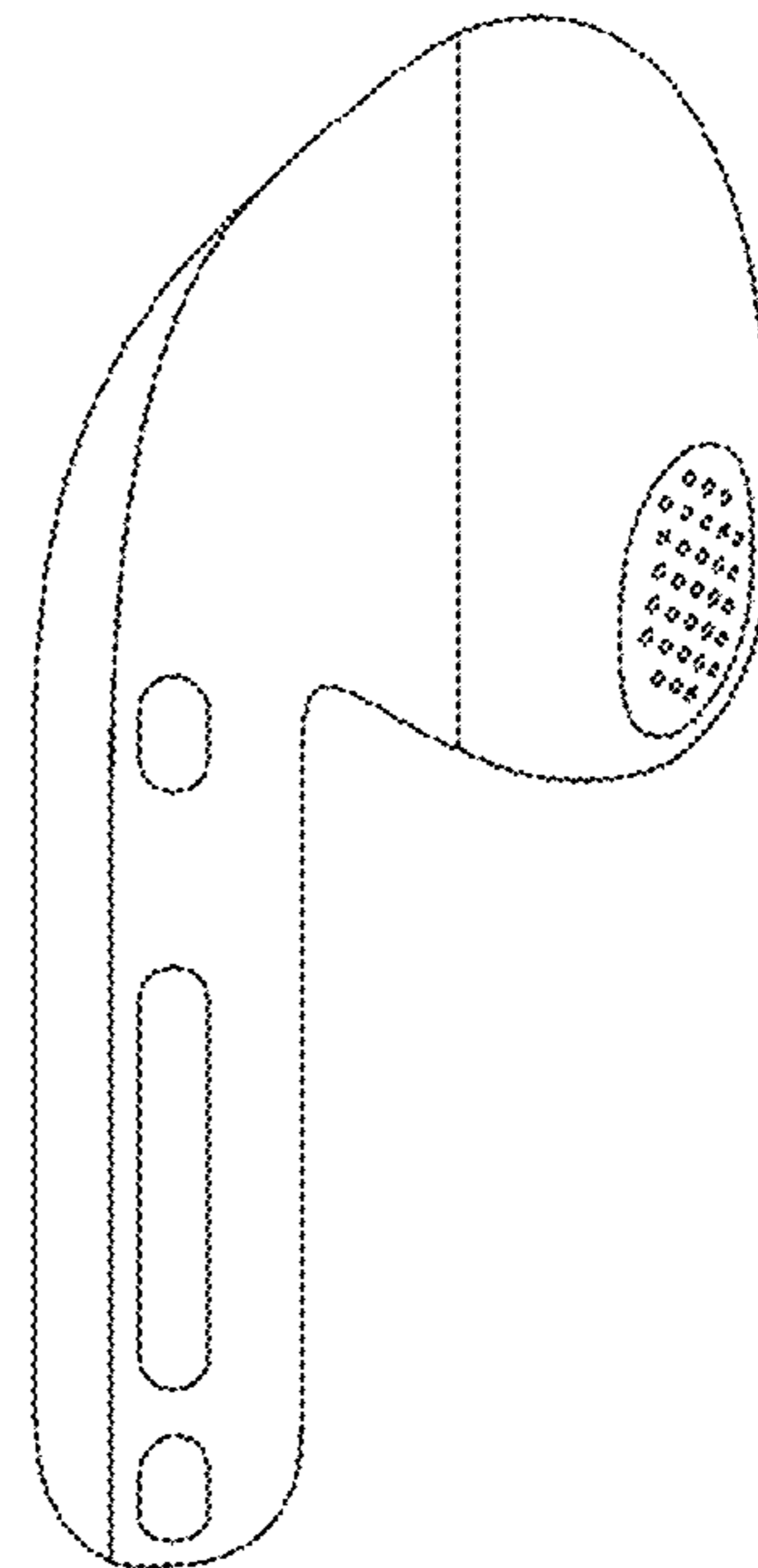
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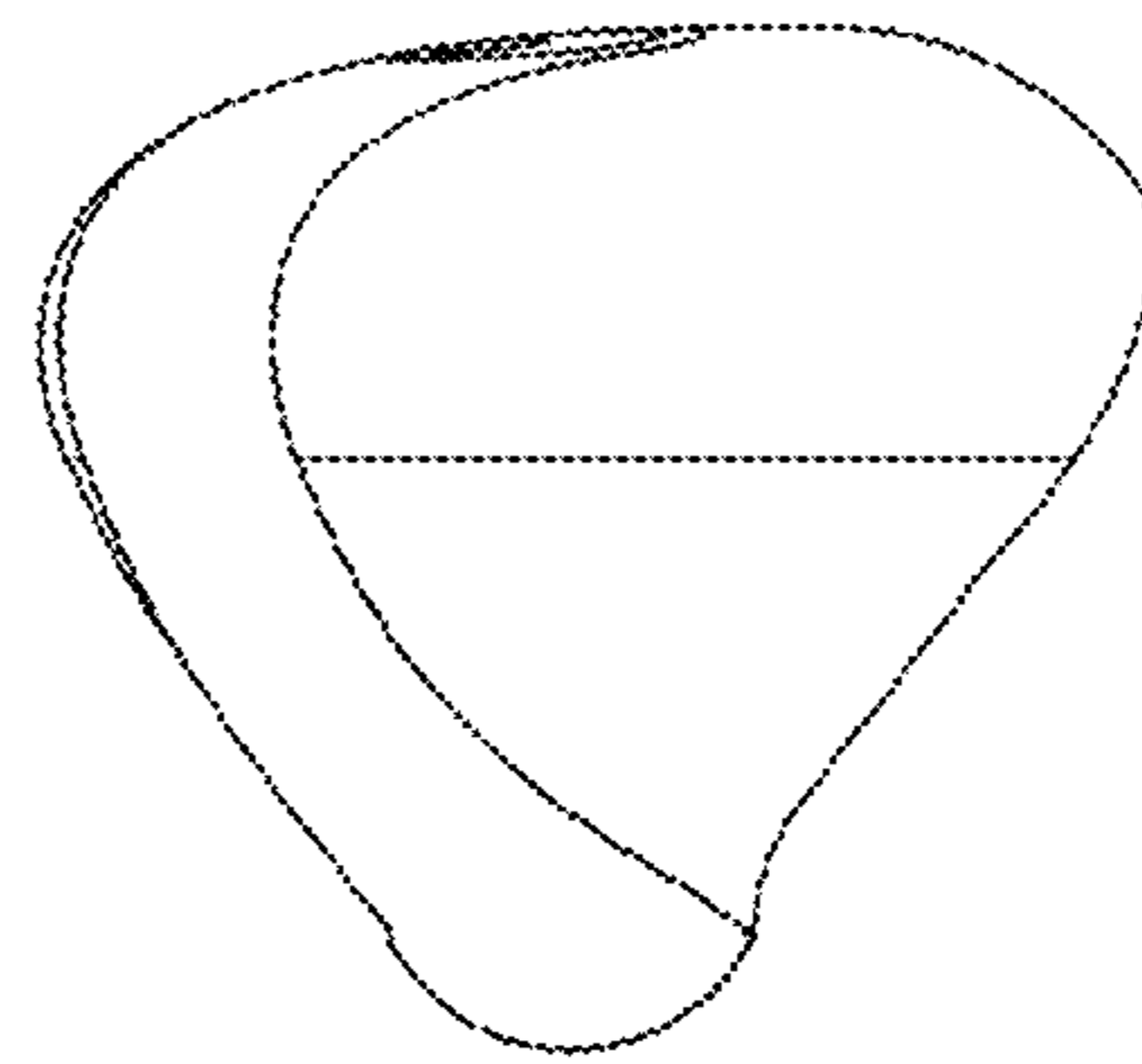
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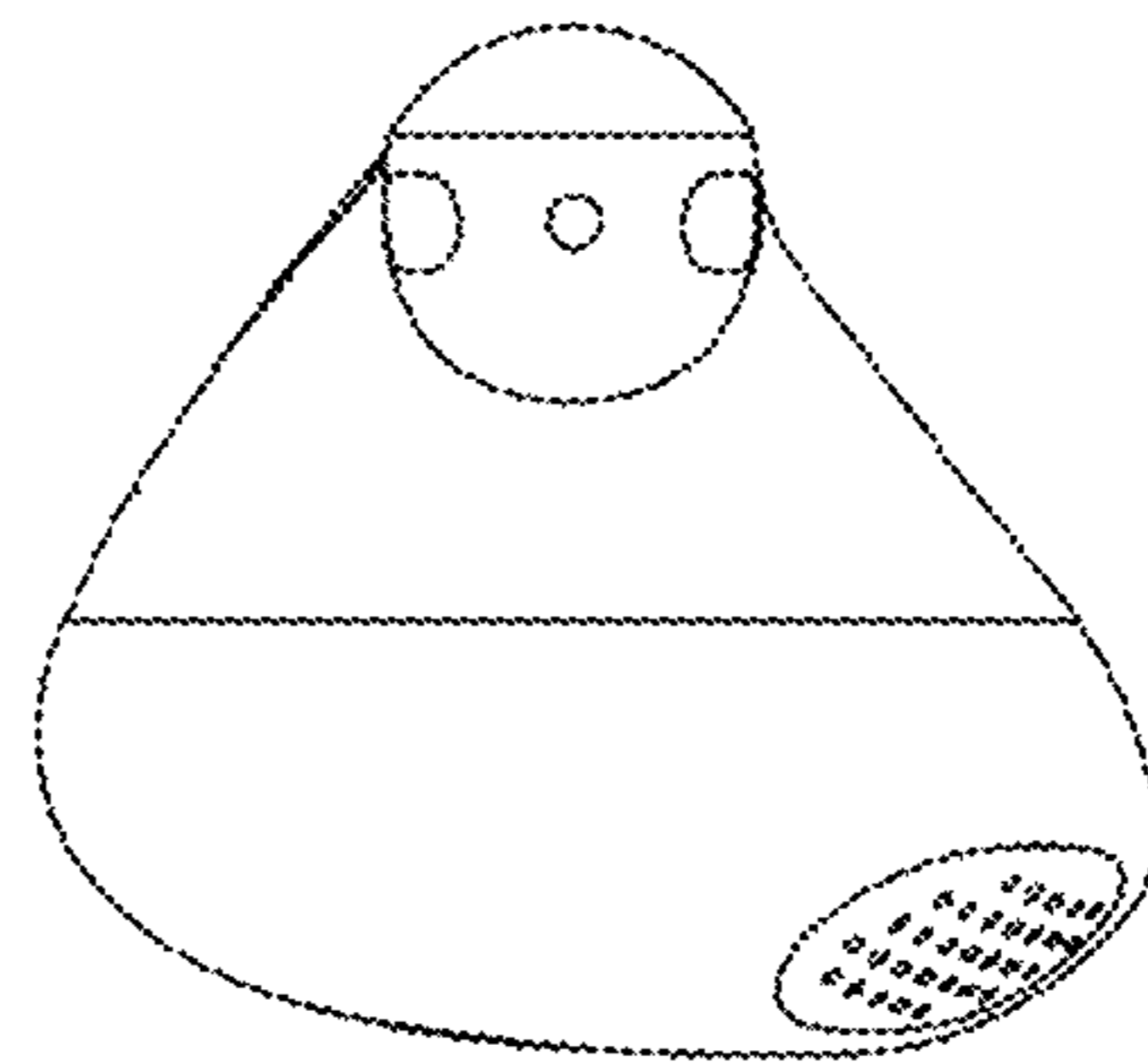
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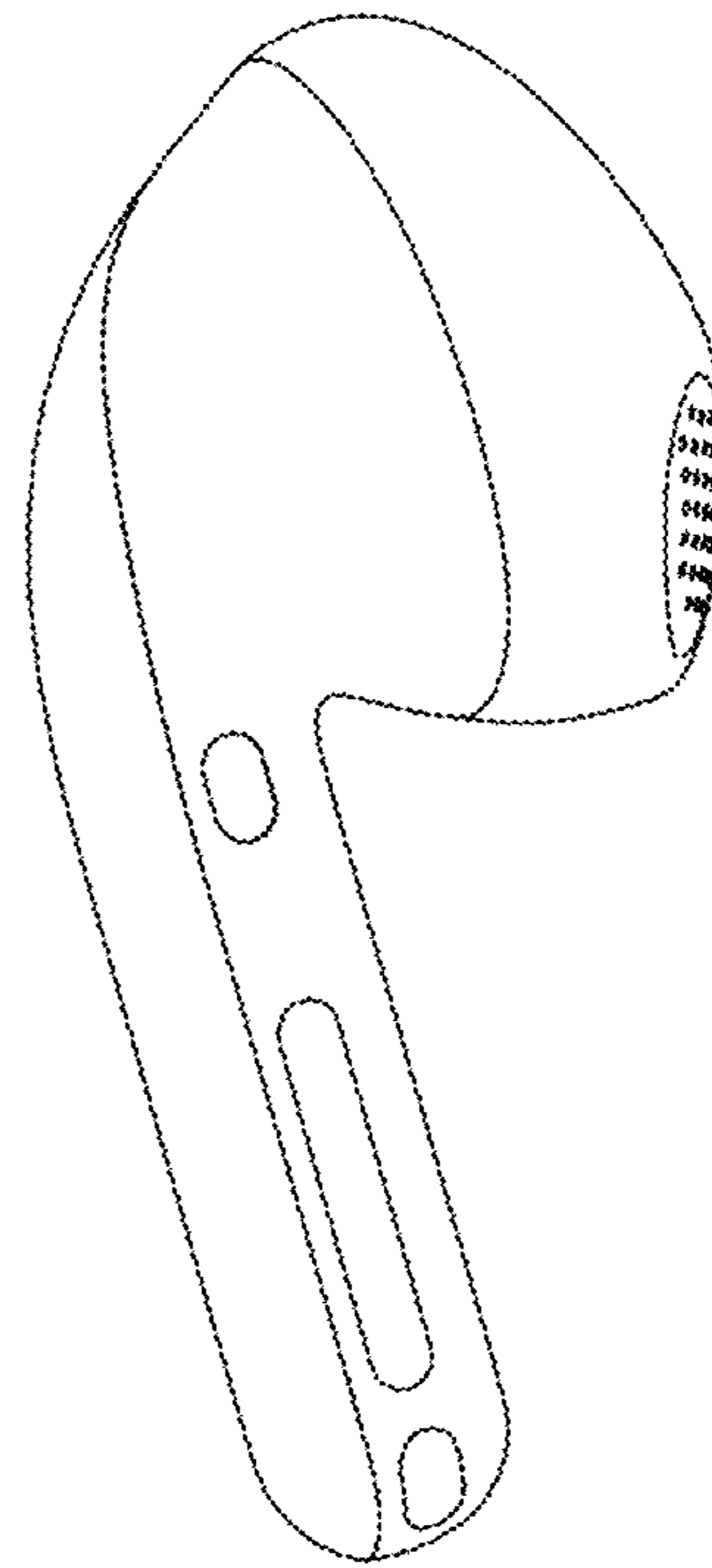


1.6





1.7



1.8

